

STM32WB07_QFN48_2L_SMD

MB2173

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Sheet 1: Project overview (this page)

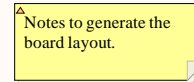
Sheet 2: STM32WB07_QFN48_RefBoard_SMD_2Layers

Legend

General comment such as function title, configuration, ...

Text to be added to silkscreen.

Warning text.



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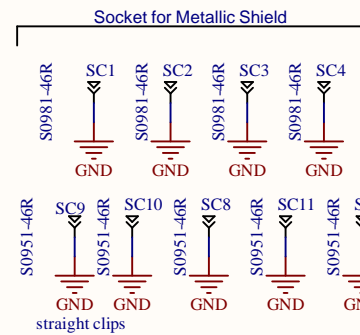
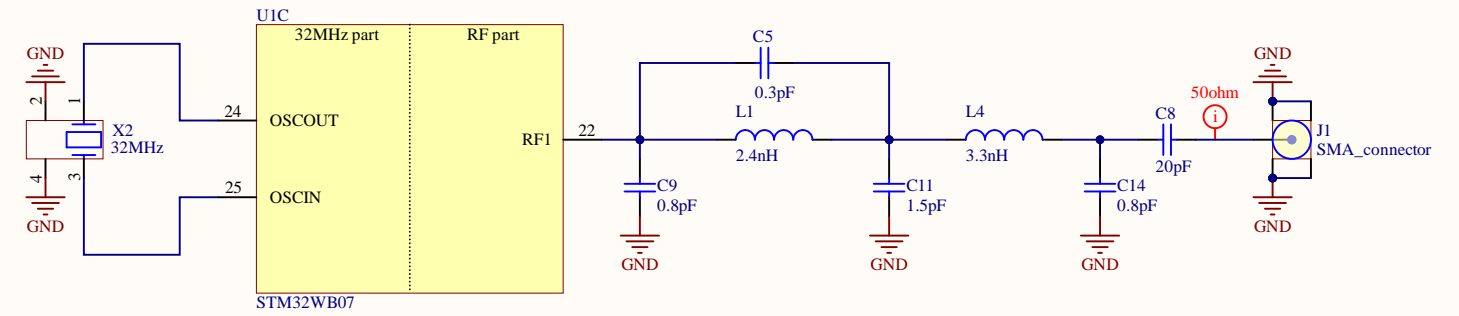
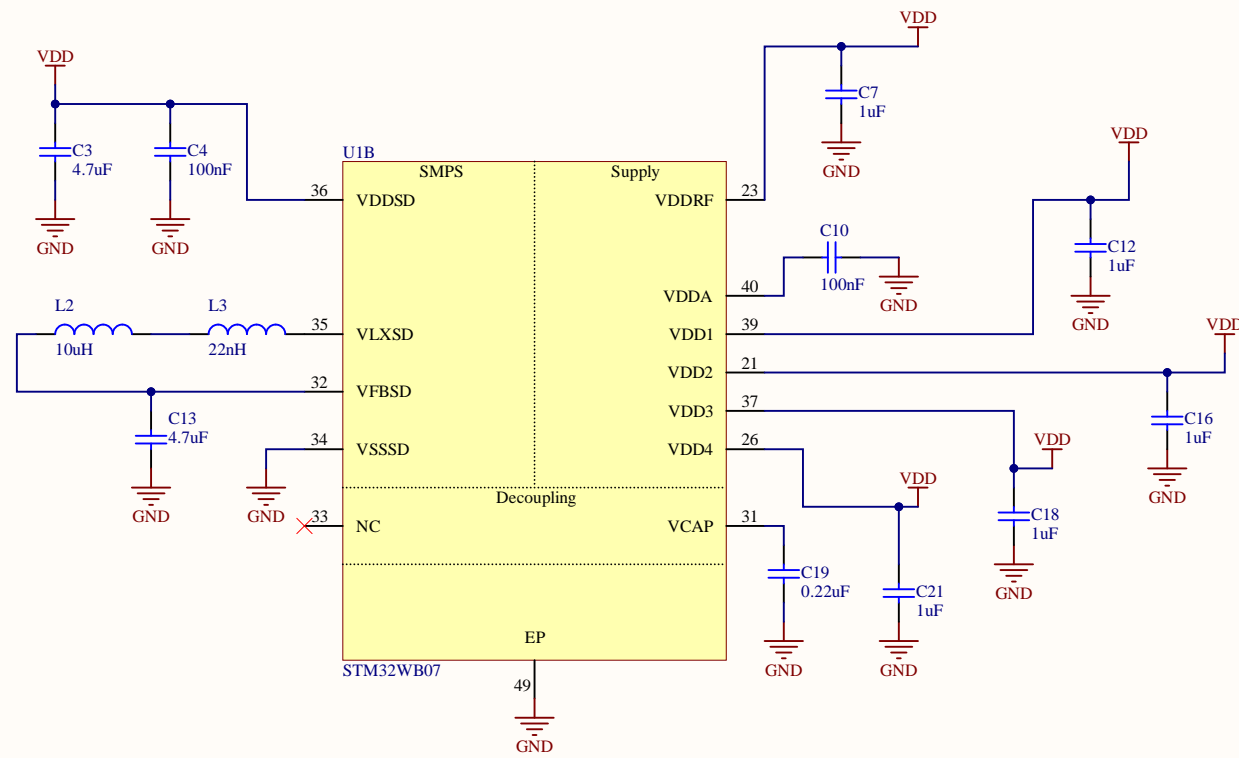
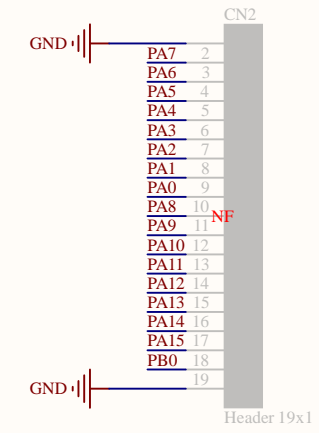
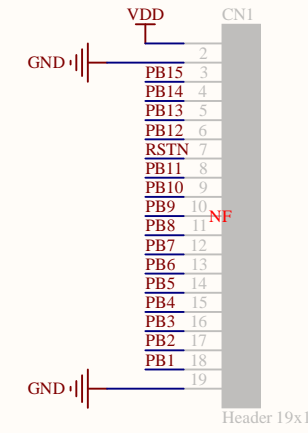
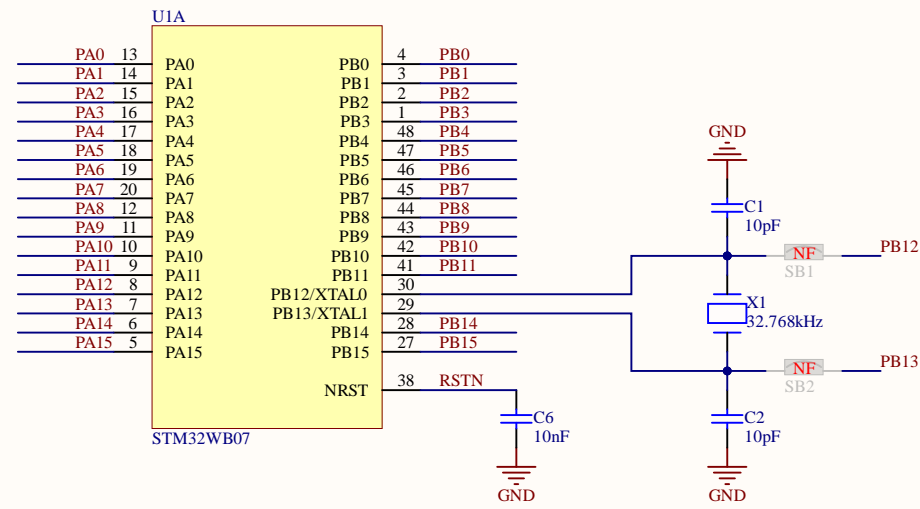
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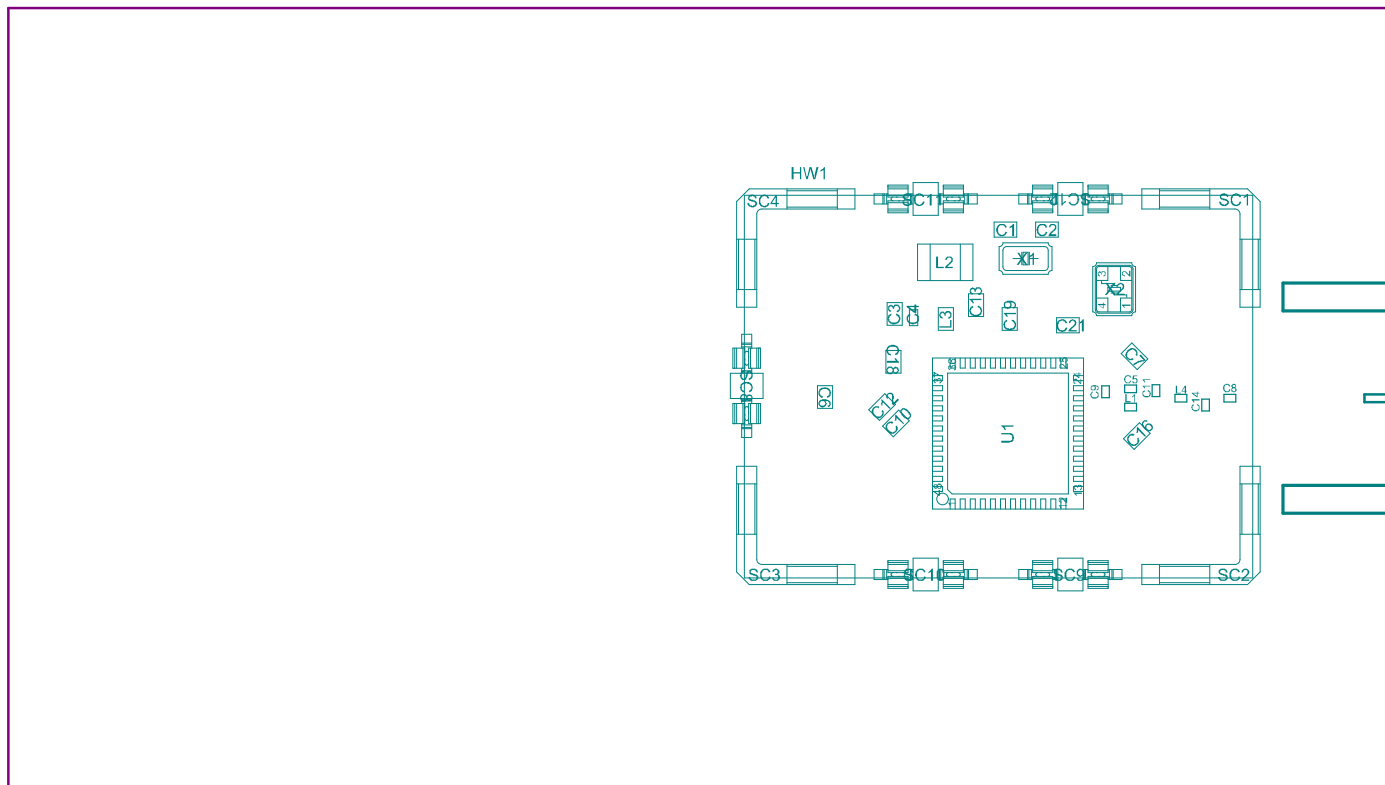
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STM32WB07_QFN48_RefBoard_SMD_2Layers.SchDoc



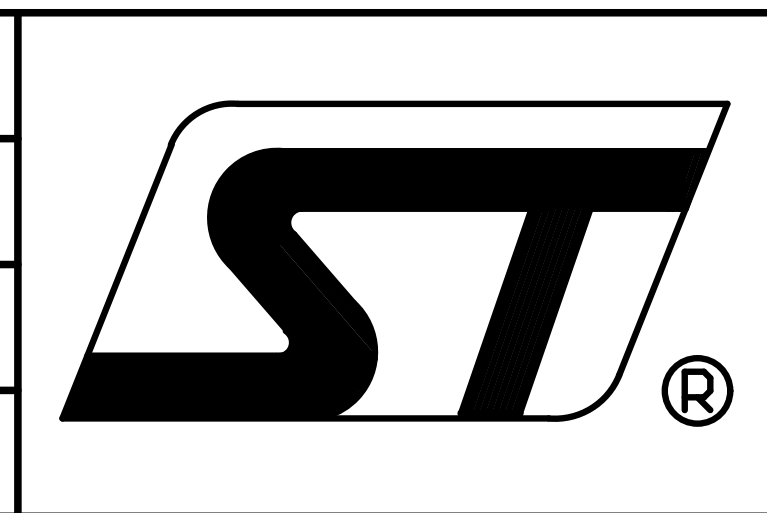
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Project: STM32WB07_QFN48_2L_SMD		
Variant: Variant A		
Revision: A-01		Reference: MB2173
Size: A4	Date: 7 July 2024	Sheet: 1 of 7

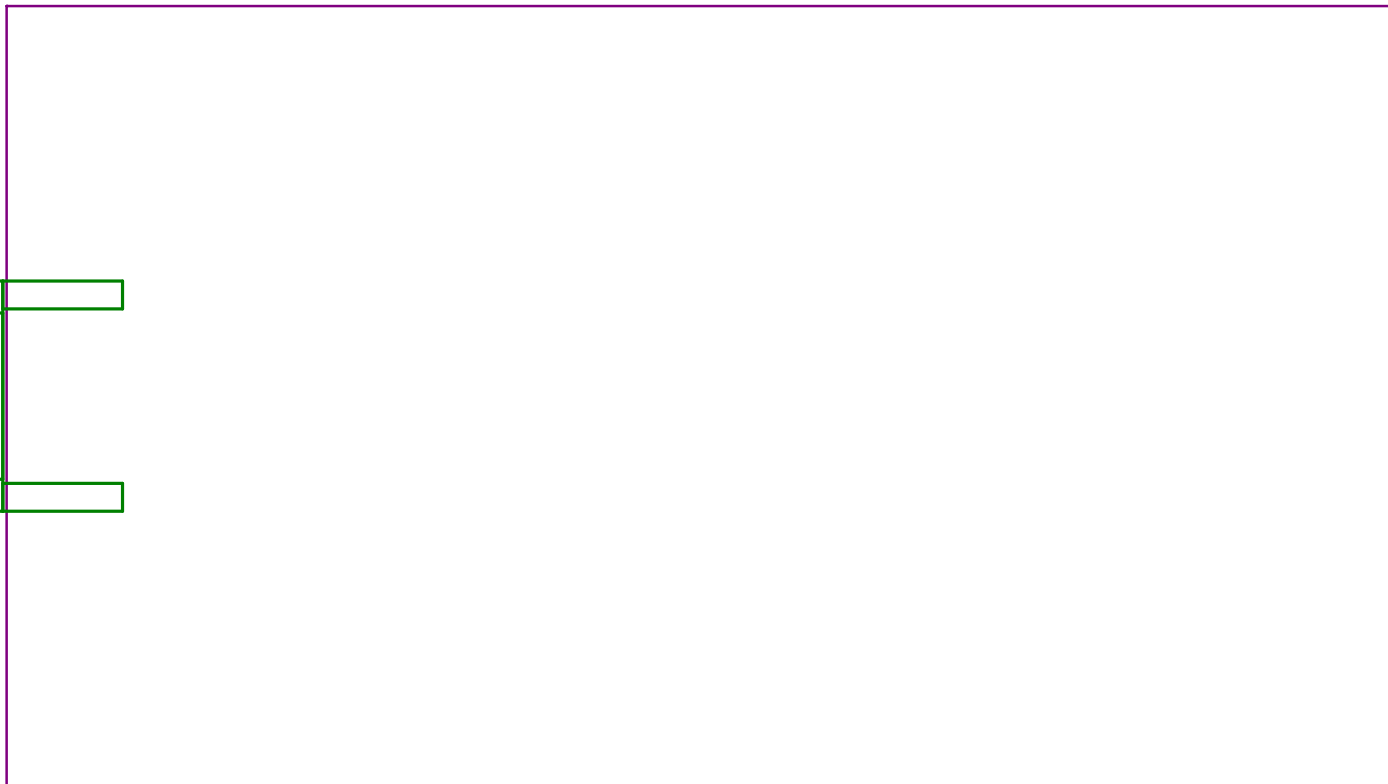
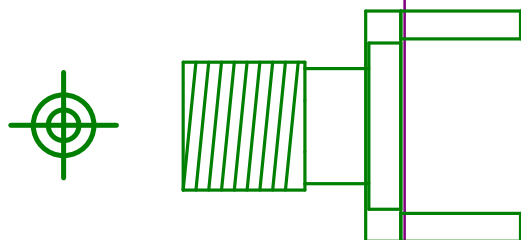






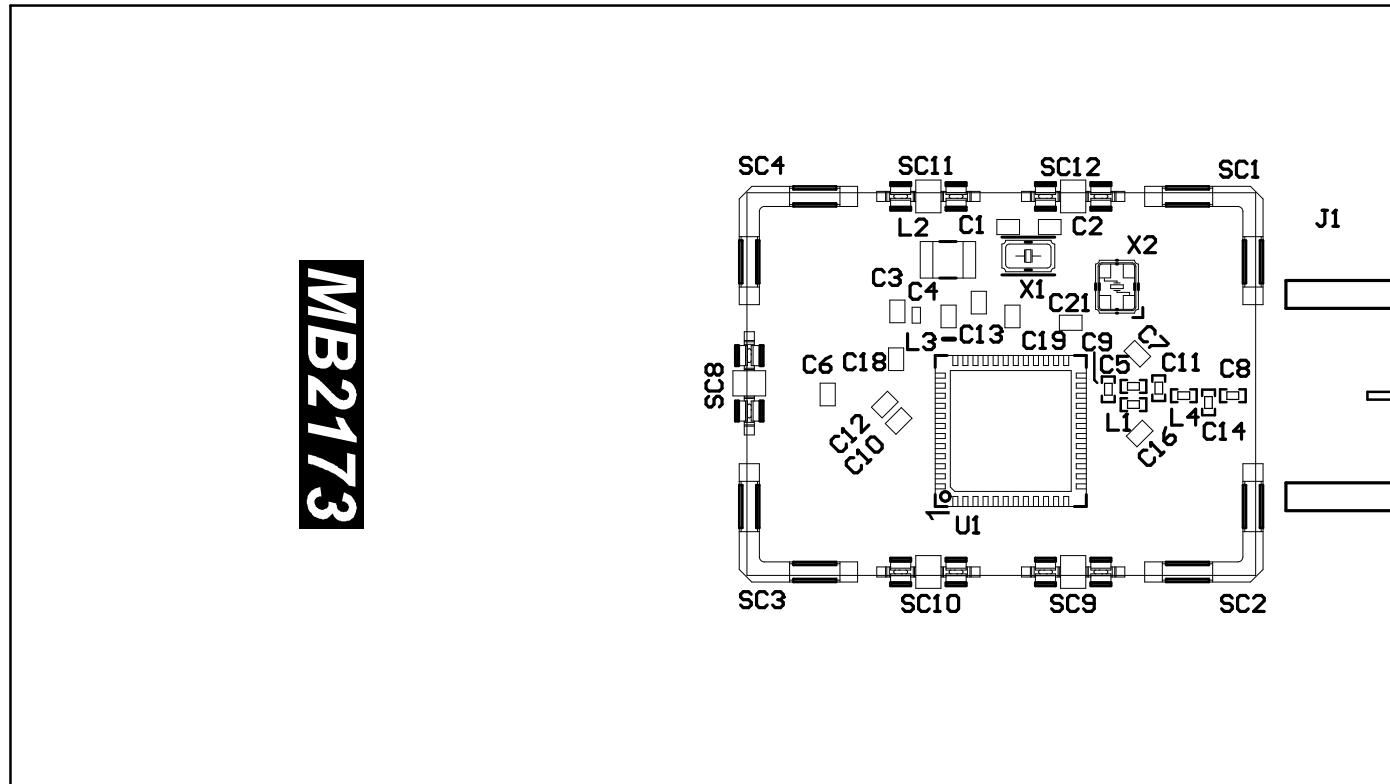
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Layer: Mechanical 14	Gerber: .GM14
Variant: Variant A	Ref: MB2173
Date: 7 July 2024	Rev: A





Project: STM32WB07_QFN48_2L_SMD	
Layer: Mechanical 15	Gerber: .GM15
Variant: Variant A	Ref: MB2173
Date: 7 July 2024	Rev: A





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